

## N-Channel 60V(D-S) MOSFET

Product summary		
$V_{DS}$	60	V
$R_{DS(ON)}$ (at $V_{GS}=10V$ ) Typ.	7.5	m $\Omega$
$I_D(T_C=25^{\circ}C)$	55	A

### Features

- Advanced Trench Technology
- Low Gate Charge

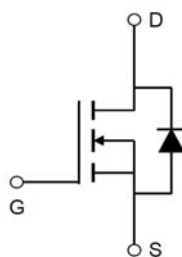
### Applications

- PWM Application
- Load switching

### Pin Configuration



TO-252



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECFA55N06	TO-252	13"	2500pcs

### Absolute Maximum Ratings (at $T_A=25^{\circ}C$ Unless Otherwise Noted)

Symbol	Parameter		Rating	Units
$V_{DS}$	Drain-Source Voltage		60	V
$V_{GS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C=25^{\circ}C$	55	A
		$T_C=100^{\circ}C$	34.8	A
$I_{DM}$	Pulse Drain Current Tested <sup>A</sup>		230	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>B</sup>		121	mJ
$P_D$	Power Dissipation	$T_C=25^{\circ}C$	58	W
$T_J, T_{STG}$	Junction and Storage Temperature Range		-55 to +150	$^{\circ}C$

### Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JC}$	Thermal Resistance-Junction to case	2.16	$^{\circ}C/W$

**Electrical Characteristics (at  $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)**

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V,I <sub>D</sub> =250uA	60	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =60V,V <sub>GS</sub> =0V	--	--	1	uA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> =0V,V <sub>GS</sub> =±20V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250uA	2.0	3.0	4.0	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>C</sup>	V <sub>GS</sub> =10V,I <sub>D</sub> =20A	--	7.5	9.8	mΩ
Dynamic Parameters <sup>D</sup>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V,V <sub>DS</sub> =25V f=1MHZ	--	2800	--	pF
C <sub>oss</sub>	Output Capacitance		--	196	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	172	--	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30V,I <sub>D</sub> =30A V <sub>GS</sub> =0 to 10V	--	85	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	17	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	9	--	nC
t <sub>D(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =30V, I <sub>D</sub> =30A, R <sub>GEN</sub> =1.8Ω, V <sub>GS</sub> =10V	--	15	--	ns
t <sub>r</sub>	Turn-on Rise Time		--	80	--	ns
t <sub>D(off)</sub>	Turn-off Delay Time		--	55	--	ns
t <sub>f</sub>	Turn-off Fall Time		--	110	--	ns
Drain-Source Diode Characteristics						
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current		--	--	55	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current		--	--	230	A
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =30A,V <sub>GS</sub> =0V	--	--	1.2	V
t <sub>rr</sub>	Reverse recovery time	I <sub>F</sub> =30A, di/dt=100 A/us	--	28	--	ns
Q <sub>rr</sub>	Reverse recovery charge		--	33	--	nC

A. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

B. EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{DD}=30V$ ,  $V_G=10V$ ,  $R_G=25\Omega$ ,  $L=0.5\text{mH}$ ,  $I_{AS}=22A$ .

C. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty cycle  $\leq 0.5\%$ .

D. Guaranteed by design, not subject to production testing.

## Typical Characteristics

Figure 1: Power De-rating

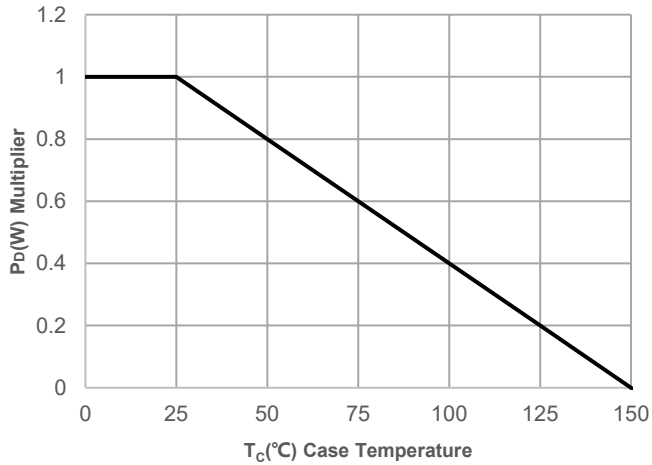


Figure 2: Current De-rating

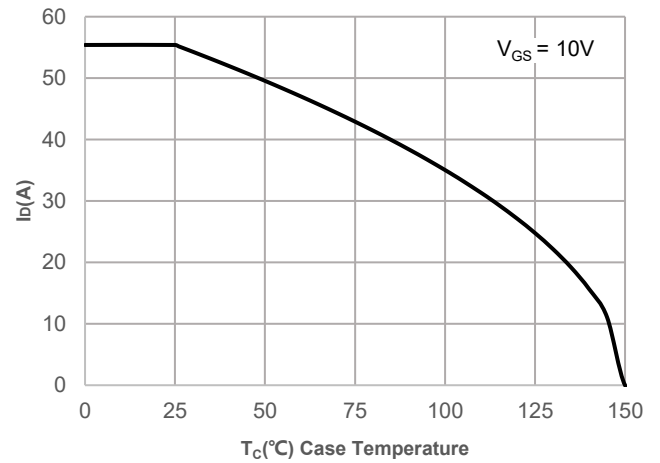


Figure 3: Normalized Maximum Transient Thermal Impedance

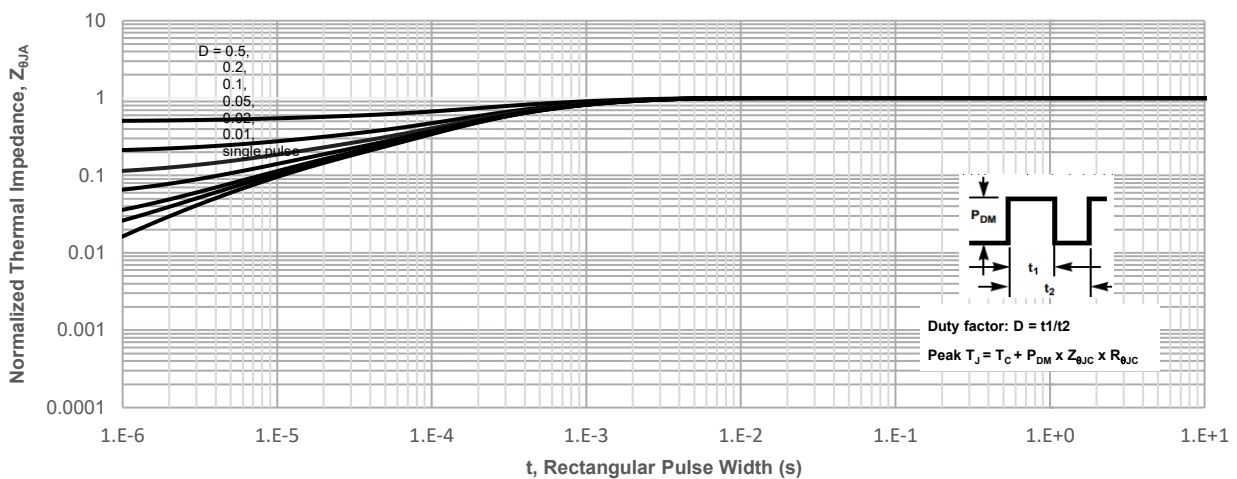
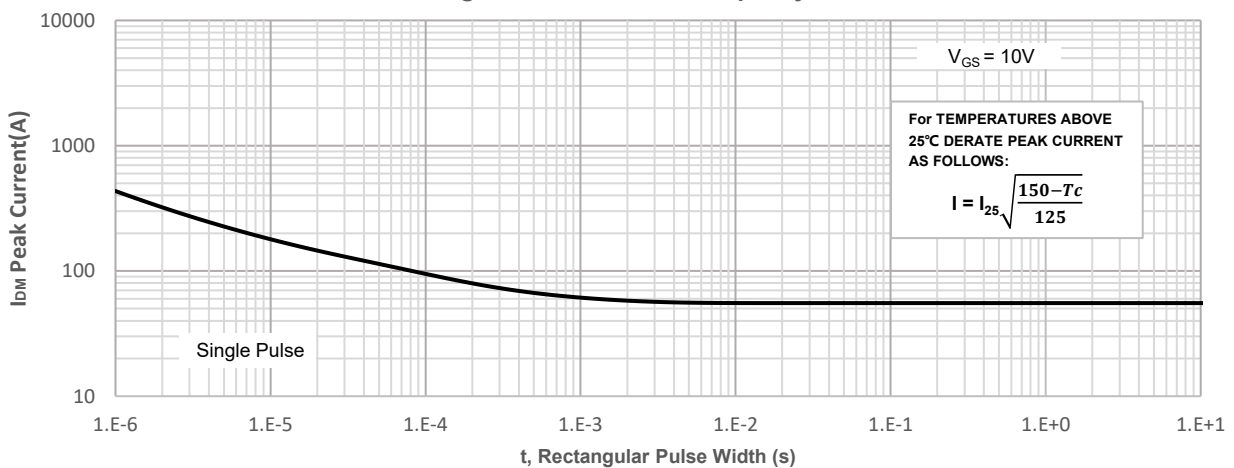


Figure 4: Peak Current Capacity



## Typical Characteristics

Figure 5: Output Characteristics

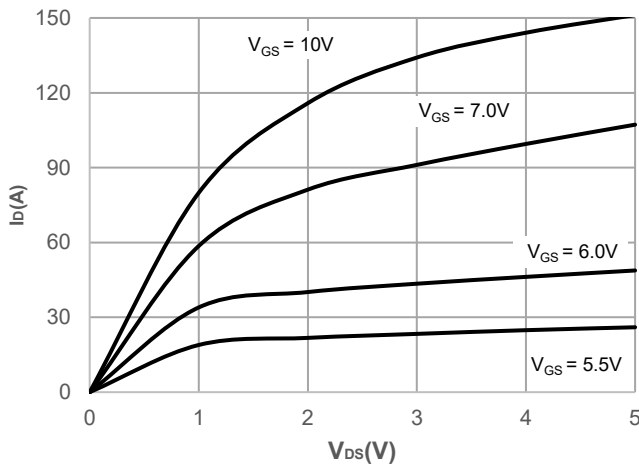


Figure 6: Typical Transfer Characteristics

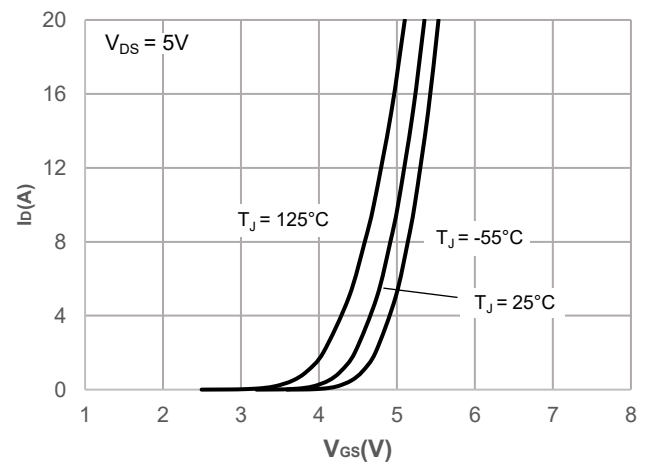


Figure 7: On-resistance vs. Drain Current

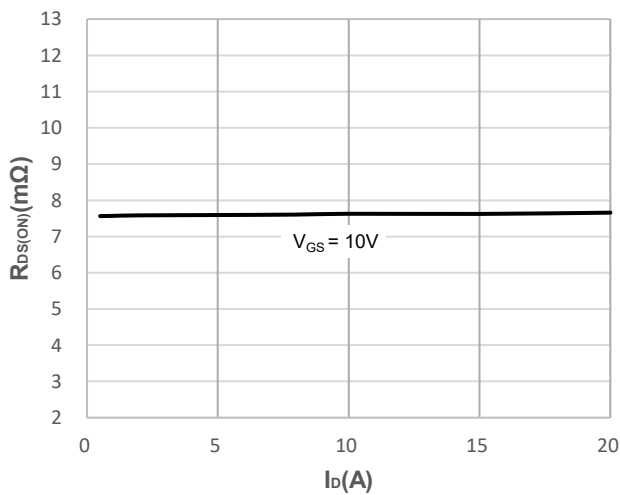


Figure 8: Body Diode Characteristics

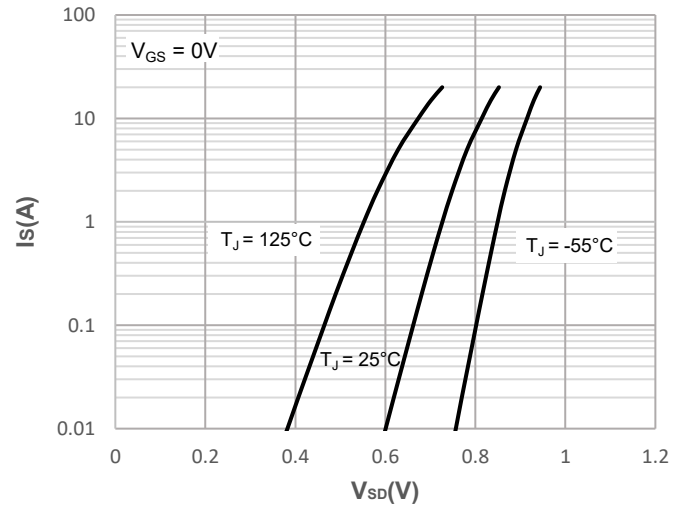


Figure 9: Gate Charge Characteristics

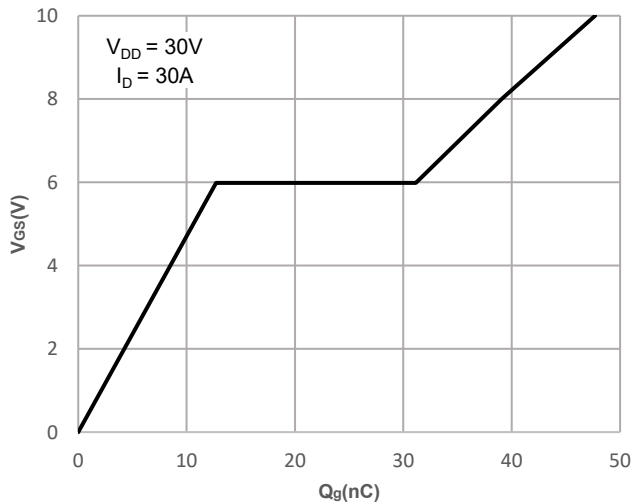
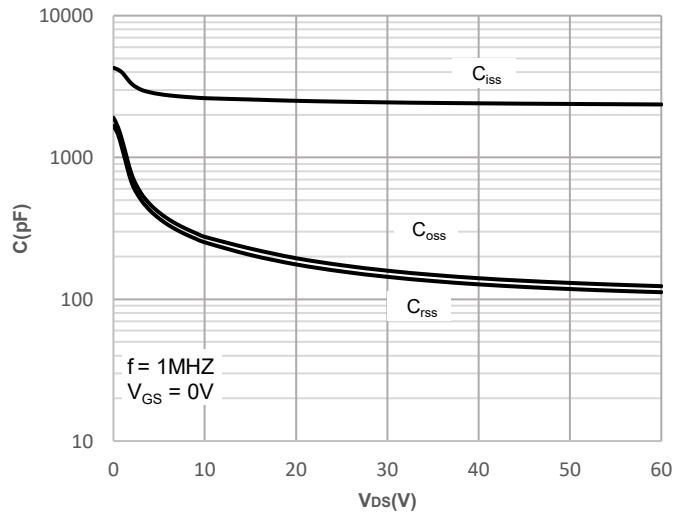
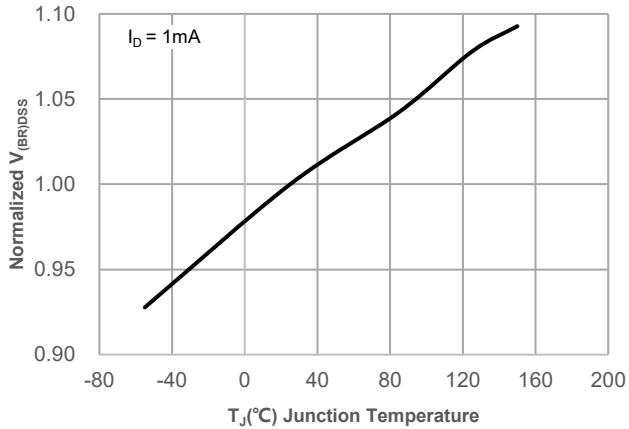


Figure 10: Capacitance Characteristics

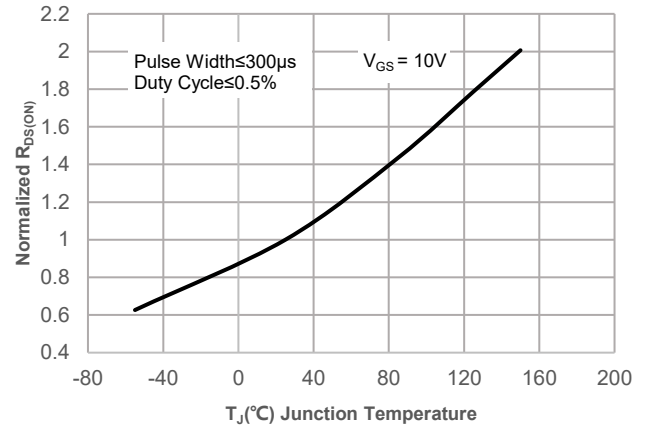


## Typical Characteristics

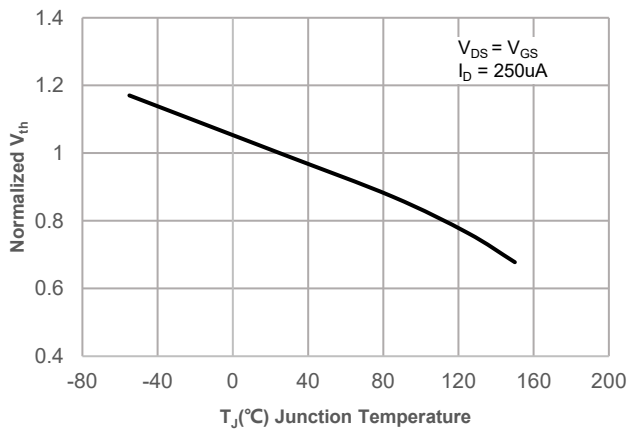
**Figure 11: Normalized Breakdown voltage vs. Junction Temperature**



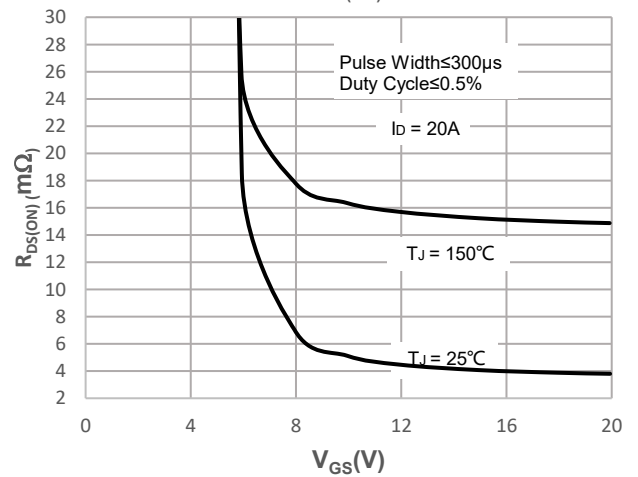
**Figure 12: Normalized on Resistance vs. Junction Temperature**



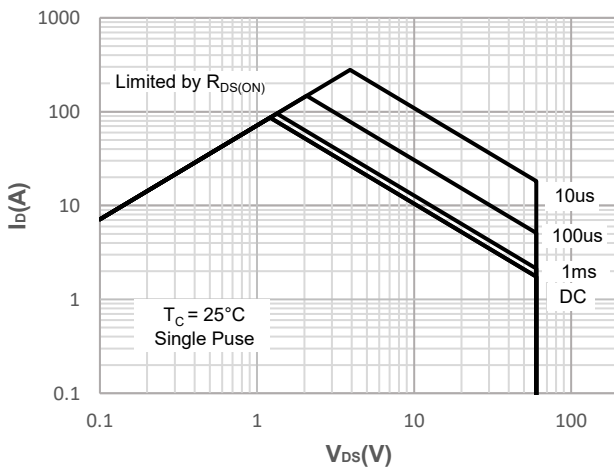
**Figure 13: Normalized Threshold Voltage vs. Junction Temperature**



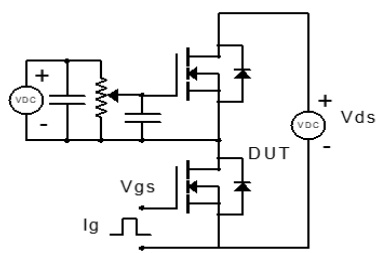
**Figure 14:  $R_{DS(ON)}$  vs.  $V_{GS}$**



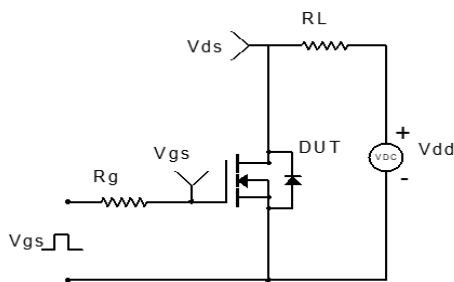
**Figure 15: Maximum Safe Operating Area**



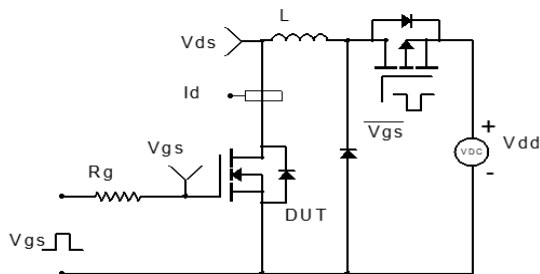
## Test Circuit



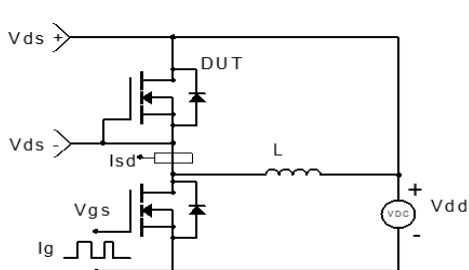
**Figure 1: Gate Charge Test Circuit & Waveform**



**Figure 2: Resistive Switching Test Circuit & Waveform**

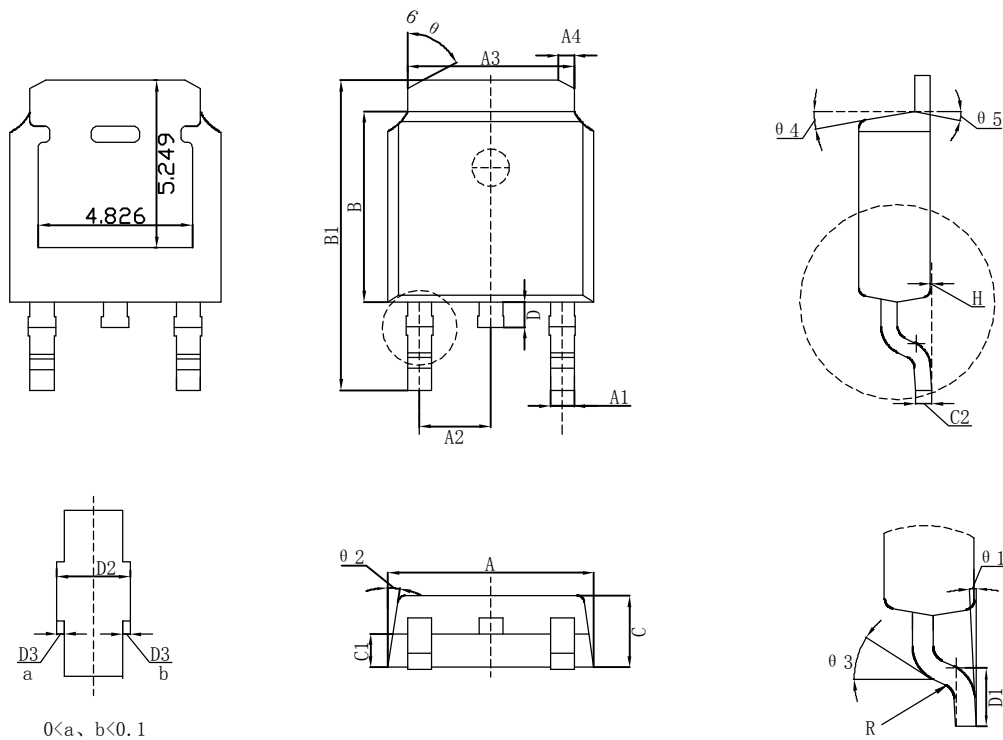


**Figure 3: Unclamped Inductive Switching Test Circuit& Waveform**



**Figure 4: Diode Recovery Test Circuit & Waveform**

## TO-252 Package Information



标注	尺寸	最小 (mm)	最大 (mm)	标注	尺寸	最小 (mm)	最大 (mm)
A		6.50	6.70	D1		1.40	1.60
A1		0.71	0.81	D2		0.81	0.91
A2		2.236	2.336	D3		0.05TYP	
A3		5.284	5.384	H		0.00	0.10
A4		0.75	0.85	R		0.40TYP	
B		6.00	6.20	$\theta 1$		$0^\circ - 8^\circ$	
B1		9.80	10.10	$\theta 2$		$8.5^\circ$ TYP4	
C		2.20	2.40	$\theta 3$		$25^\circ$ TYP	
C1		0.967	1.087	$\theta 4$		$10^\circ$ TYP2	
C2		0.498	0.518	$\theta 5$		$10^\circ$ TYP	
D		0.70	0.90	$\theta 6$		$70^\circ$ TYP	